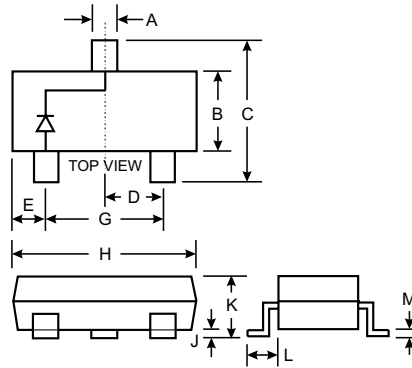


Features

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automatic Insertion
- For General Purpose Switching Applications
- High Conductance

Mechanical Data

- Case: SOT-323, Molded Plastic
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Marking: KA1
- Weight: 0.006 grams (approx.)



SOT-323		
Dim	Min	Max
A	0.30	0.40
B	1.15	1.35
C	2.00	2.20
D	0.65 Nominal	
E	0.30	0.40
G	1.20	1.40
H	1.80	2.20
J	0.0	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.25
All Dimensions in mm		

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	MMBD4448H	Unit
Non-Repetitive Peak Reverse Voltage	V_{RM}	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	80	V
RMS Reverse Voltage	$V_{R(RMS)}$	57	V
Forward Continuous Current (Note 1)	I_{FM}	500	mA
Average Rectified Output Current (Note 1)	I_O	250	mA
Non-Repetitive Peak Forward Surge Current @ $t = 1.0\mu\text{s}$ @ $t = 1.0\text{s}$	I_{FSM}	4.0 2.0	A
Power Dissipation (Note 1)	P_d	200	mW
Thermal Resistance Junction to Ambient Air (Note 1)	$R_{\theta JA}$	625	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_j, T_{STG}	-65 to +150	$^\circ\text{C}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 2)	$V_{(BR)R}$	80	—	V	$I_R = 2.5\mu\text{A}$
Forward Voltage (Note 2)	V_{FM}	0.62 — — —	0.72 0.855 1.0 1.25	V	$I_F = 5.0\text{mA}$ $I_F = 10\text{mA}$ $I_F = 100\text{mA}$ $I_F = 150\text{mA}$
Peak Reverse Current (Note 2)	I_{RM}	—	100 50 30 25	nA μA μA nA	$V_R = 70\text{V}$ $V_R = 75\text{V}, T_j = 150^\circ\text{C}$ $V_R = 25\text{V}, T_j = 150^\circ\text{C}$ $V_R = 20\text{V}$
Junction Capacitance	C_j	—	3.5	pF	$V_R = 6\text{V}, f = 1.0\text{MHz}$
Reverse Recovery Time	t_{rr}	—	4.0	ns	$V_R = 6\text{V}, I_F = 5\text{mA}$

- Notes:
1. Valid provided that terminals are kept at ambient temperature.
 2. Short duration test pulse used to minimize self-heating effect.

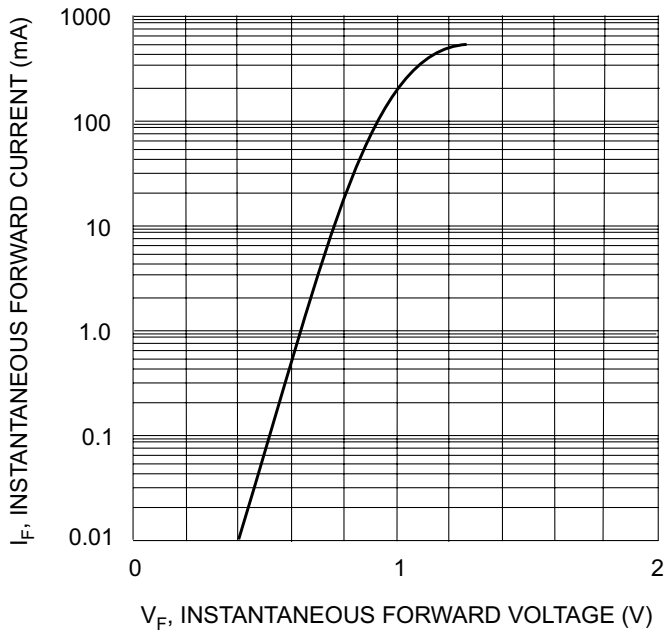


Fig. 1 Forward Characteristics

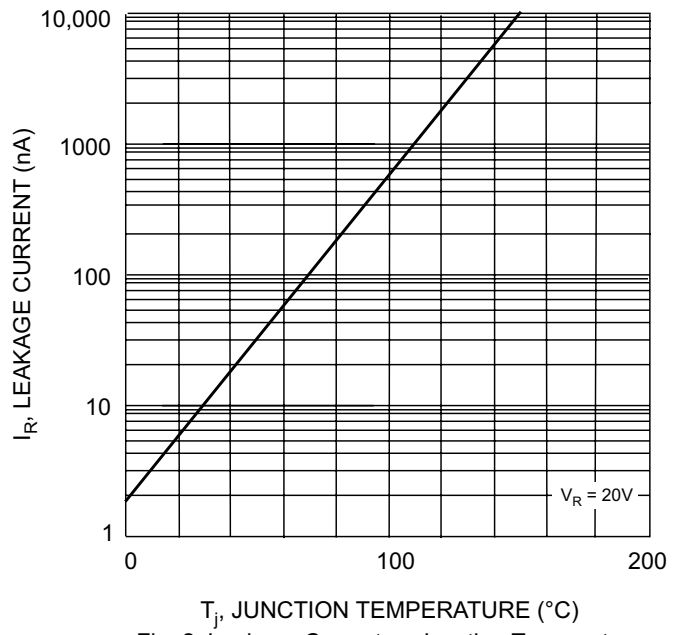


Fig. 2 Leakage Current vs Junction Temperature